

## Patent claims

1. Electrically conductive, thermoplastic and heat-activatable  
5 adhesive film, comprising
- i) a thermoplastic polymer in a proportion of from 30 to 89.9% by weight,
  - ii) one or more tackifying resins in a proportion of from 5 to 50% by weight  
and/or
  - iii) epoxy resins with hardeners, with or without accelerators, in a  
10 proportion of from 5 to 40% by weight, and
  - iv) silver-coated glass beads or silver particles in a proportion of from 0.1 to  
40% by weight,
  - v) where the diameter of the glass beads is at least equal to the thickness  
of the adhesive film.
- 15 2. Adhesive film according to Claim 1, characterized in that the  
thermoplastic polymer comprises thermoplastic polyolefins, polyesters,  
polyurethanes or polyamides or modified rubbers, such as nitrile rubbers in  
particular.
3. Adhesive film according to Claims 1 and 2, characterized in that  
20 the adhesive film is blended with one or more additives, such as colorants,  
mineral or organic fillers, such as silica, carbon powders and metal  
powders.
4. Thermoplastic adhesive film according to Claims 1 to 3,  
characterized in that the adhesive film has a thickness of from 20 to  
25 500  $\mu\text{m}$ .
5. Thermoplastic adhesive film according to Claims 1 to 4,  
characterized in that the adhesive film is suitable for hot pressing at  
temperatures below 120°C, in particular from 80 to 100°C.
6. Thermoplastic adhesive film according to Claims 1 to 5,  
30 characterized in that the adhesive film has the same dimensions as the  
module and is in the form of a punched film section.
7. Use of an adhesive film according to one of Claims 1 to 6 for  
implanting electrical modules in a card body provided with a cutout for  
accommodating an electronic module which on the first side has a plurality  
35 of contact surfaces and on the second side, which is opposite the first side,  
has an IC chip whose terminals are connected via electrical conductors to  
the contact surfaces, the adhesive film being used to connect the second  
side of the module to the card body.

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